

外壳温度的测定

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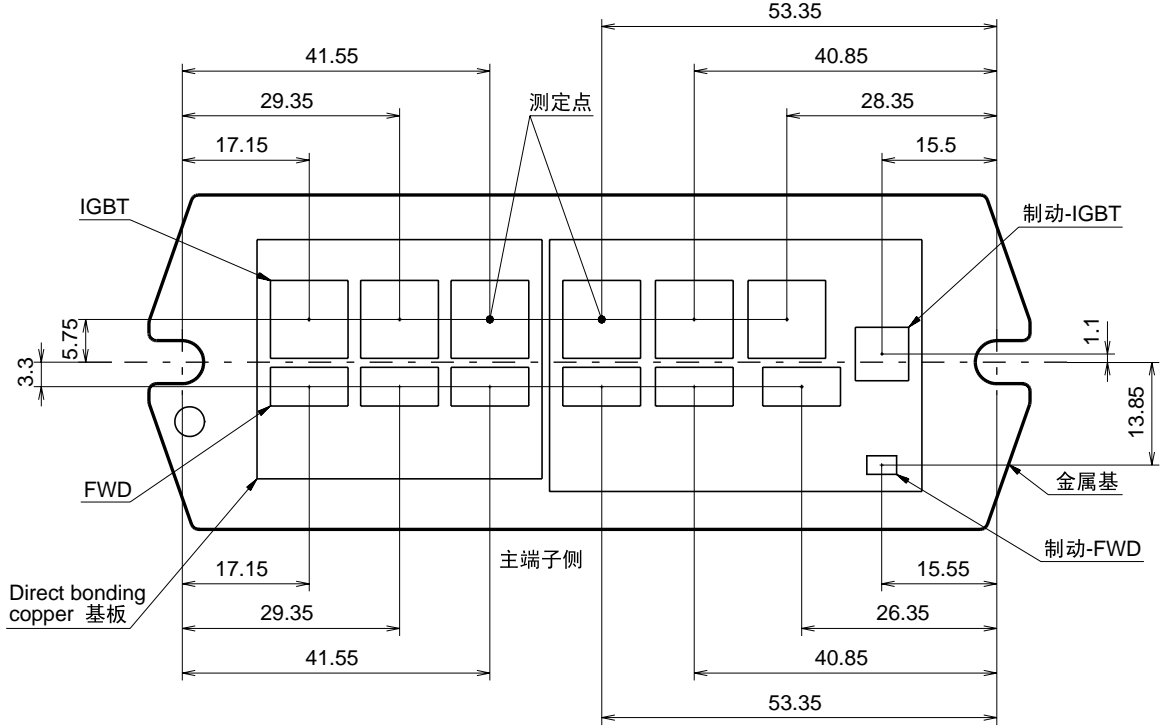
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1 Econo IPM 600V 系列 (封装: P622)

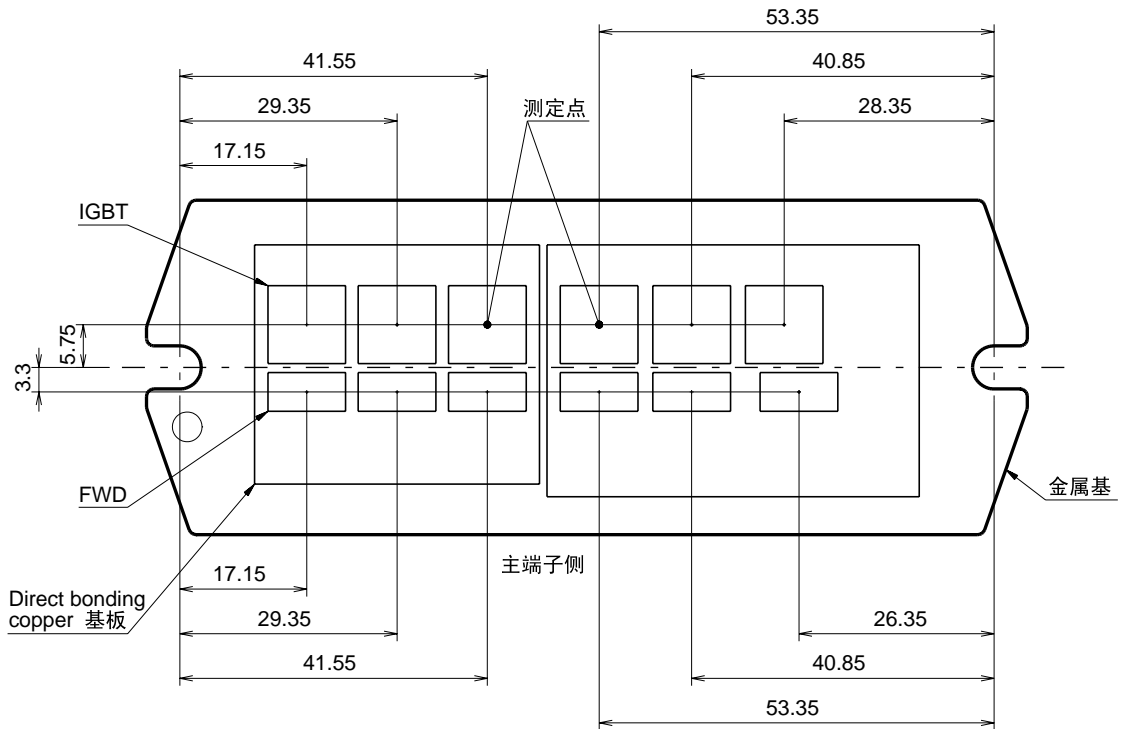
芯片配置 尺寸是 mm

1.1 600V/150A

7 in one 封装

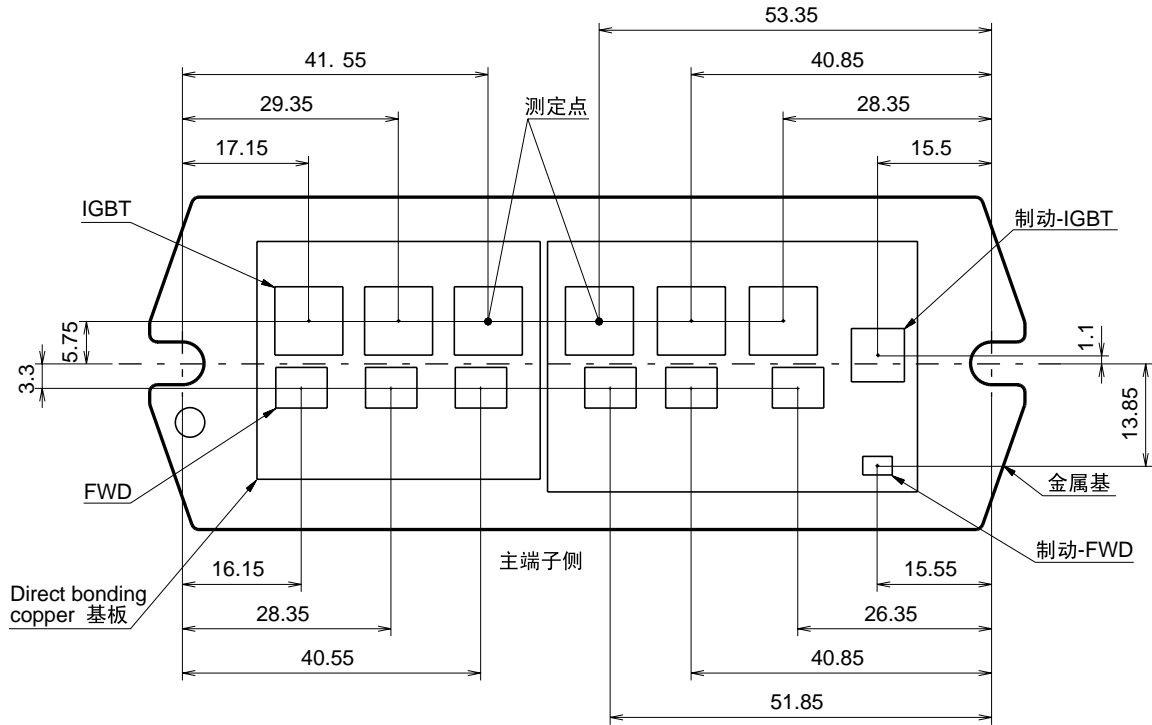


6 in one 封装

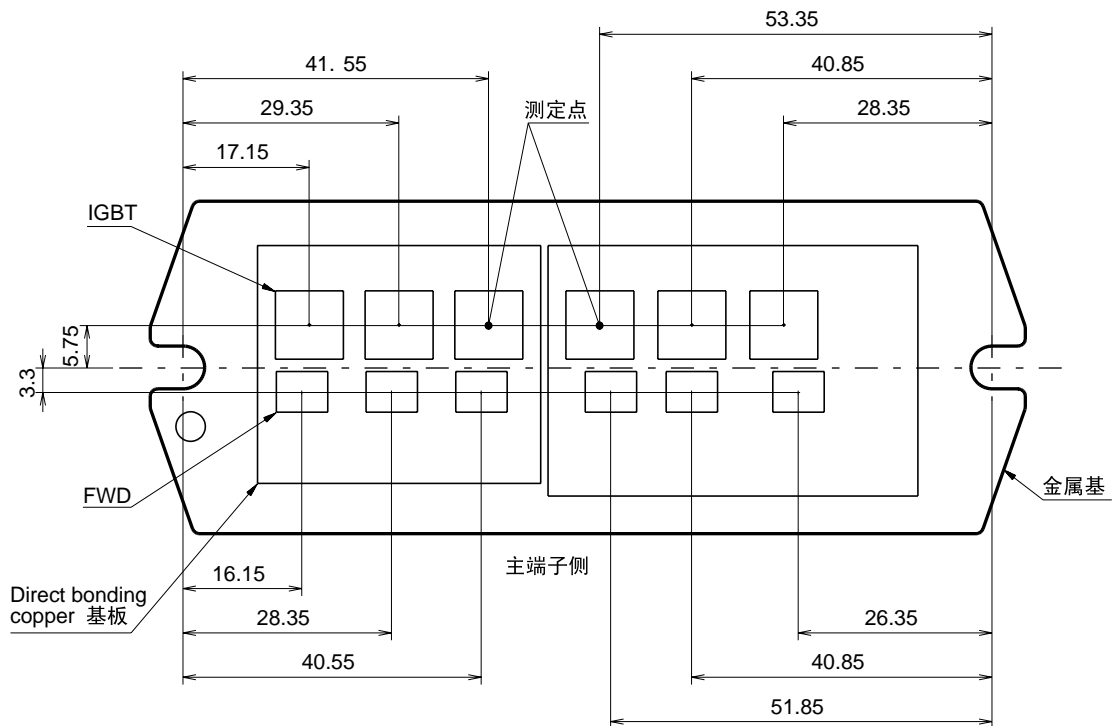


1.2 600V/100A

7 in one 封装

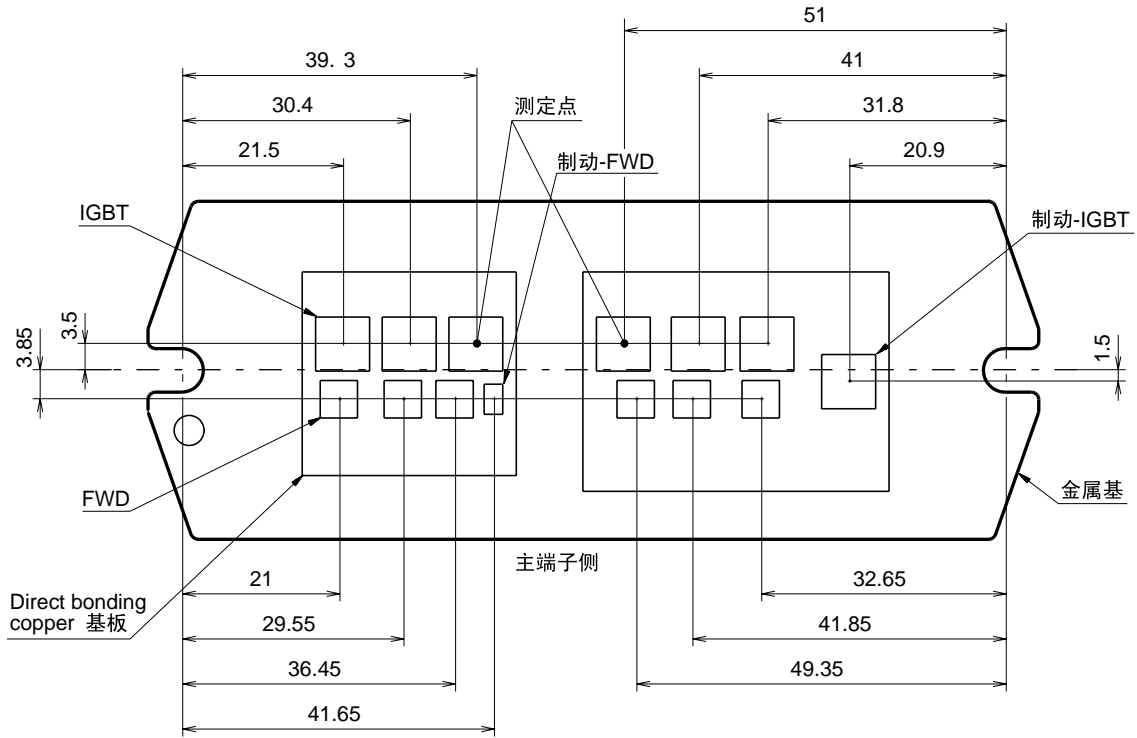


6 in one 封装

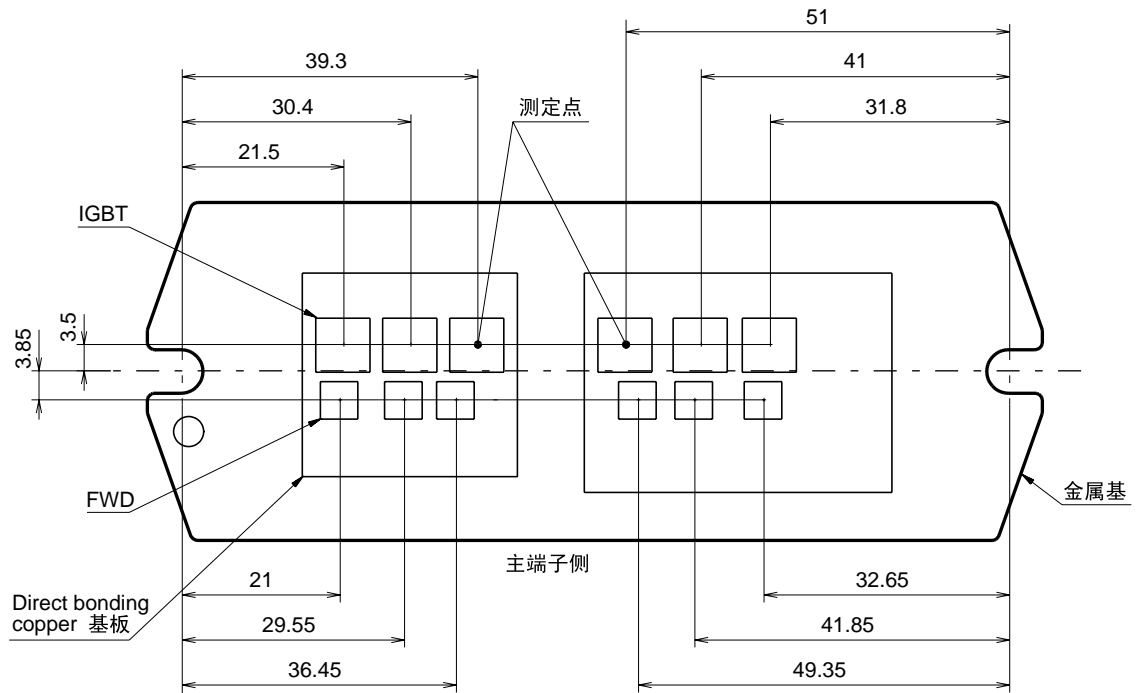


1.3 600V/75A

7 in one 封装

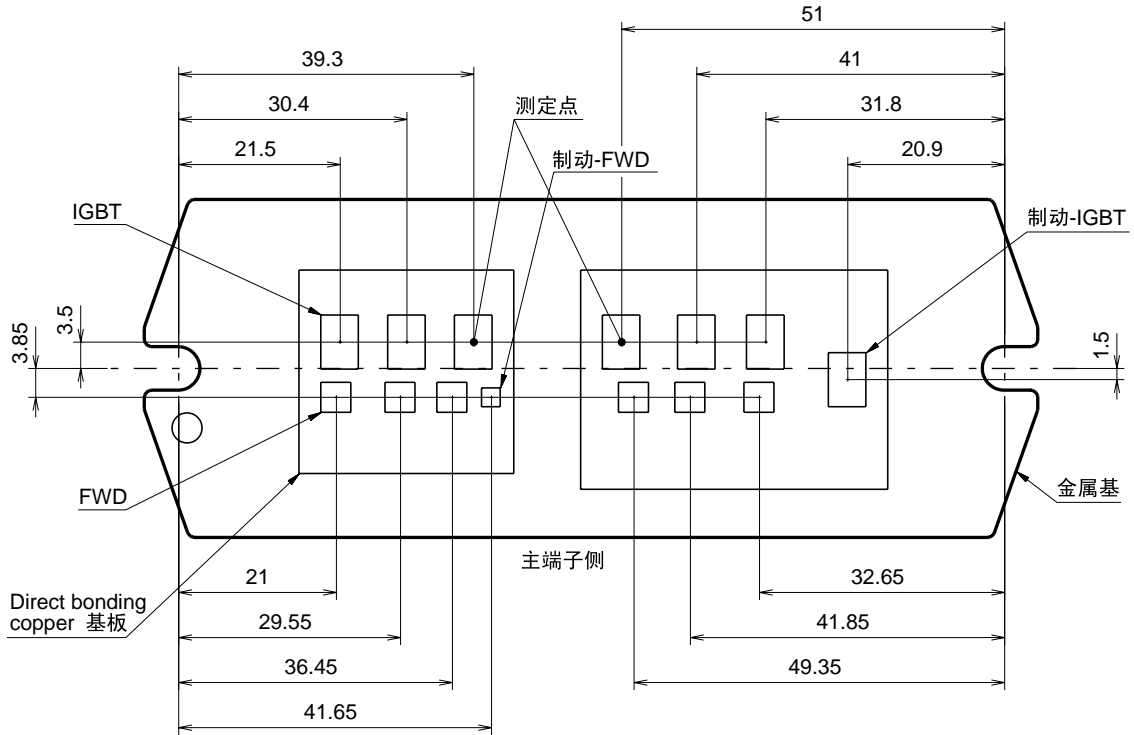


6 in one 封装

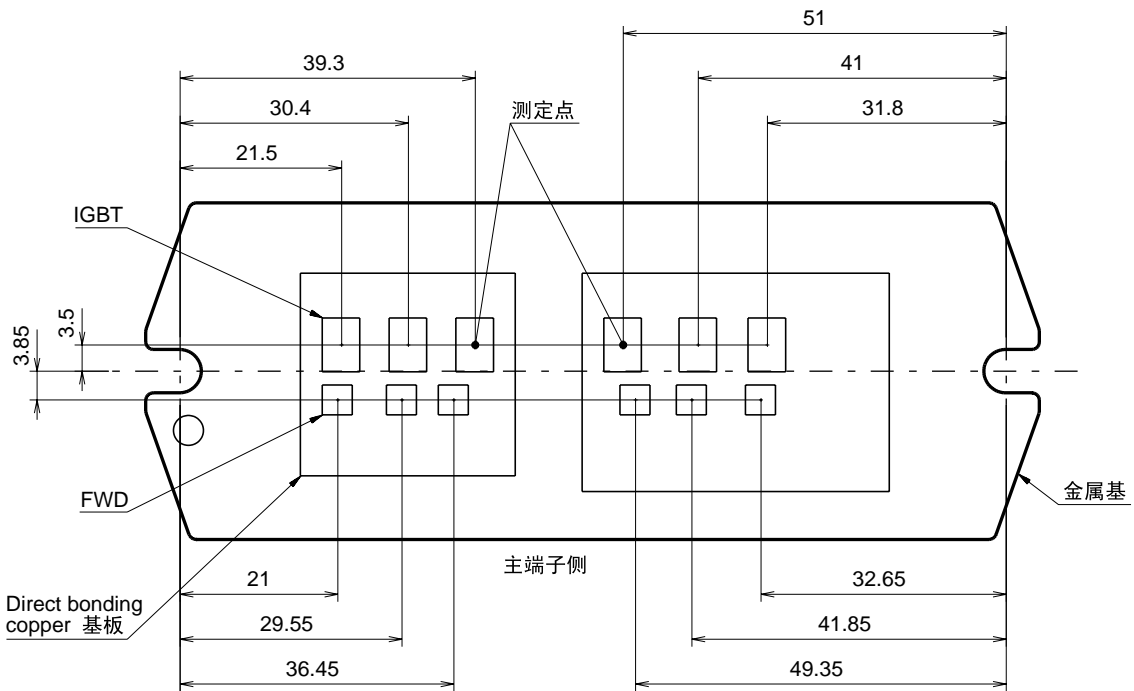


1.4 600V/50A

7 in one 封装



6 in one 封装

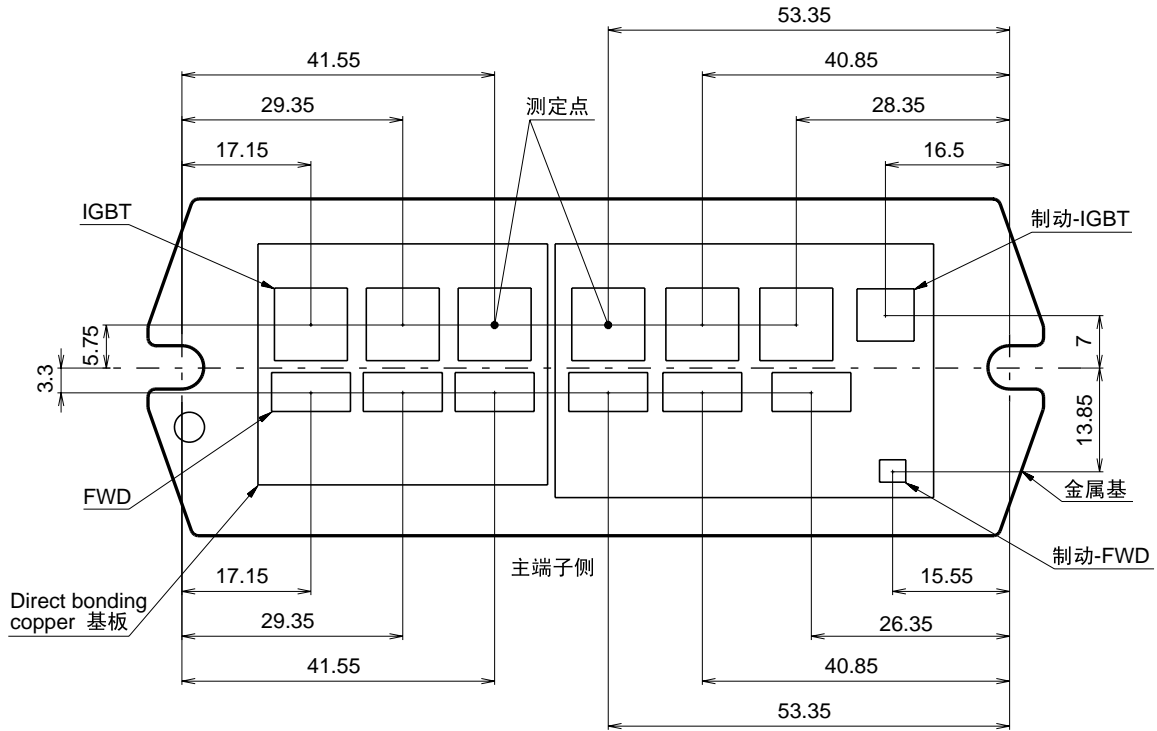


2 Econo IPM 1200V 系列（封装：P622）

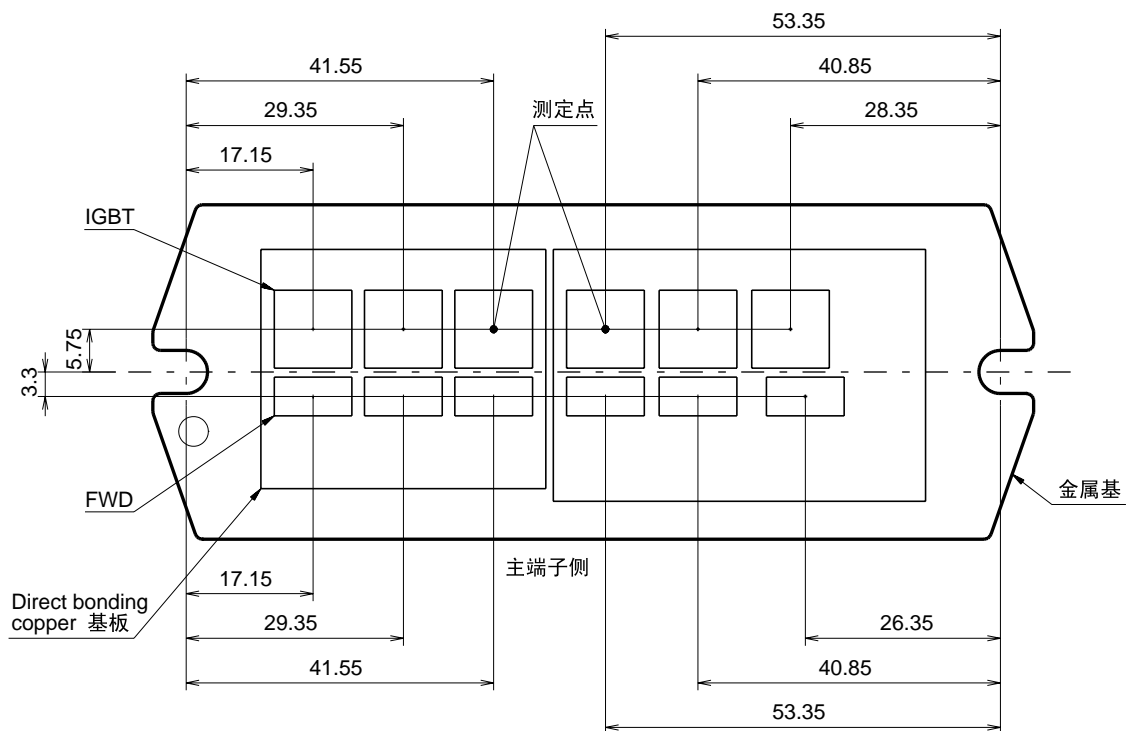
芯片配置 尺寸是 mm

2.1 1200V/75A

7 in one 封装

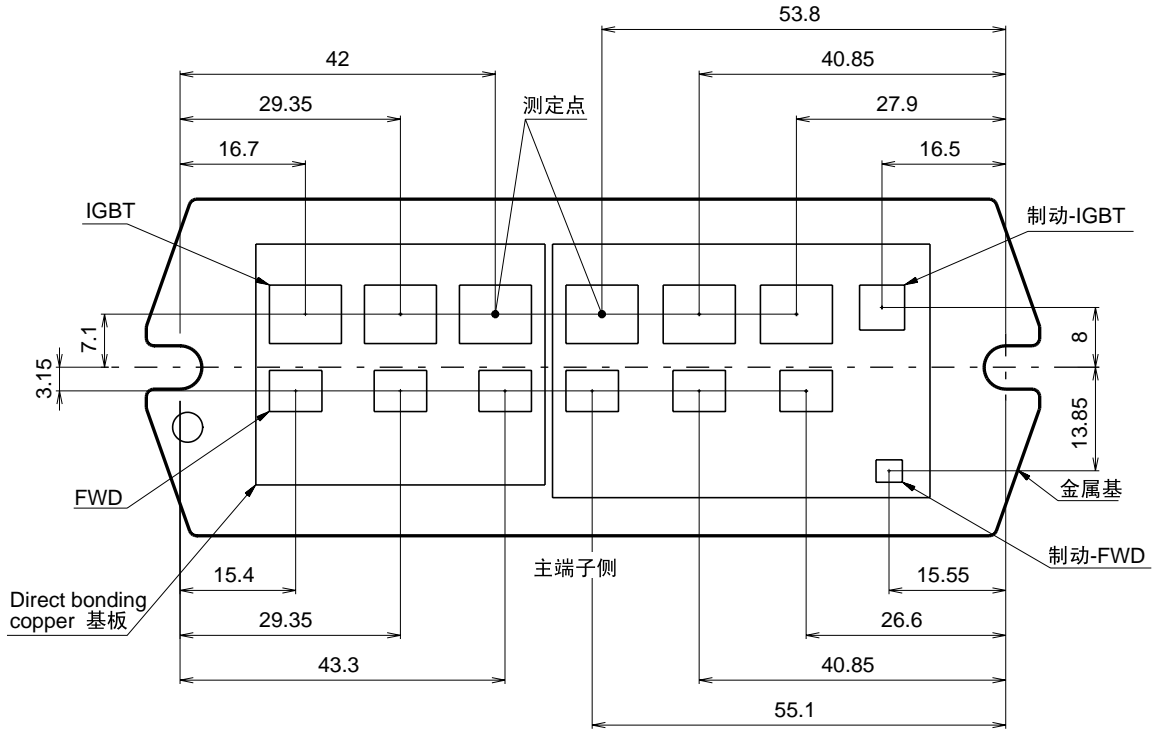


6 in one 封装

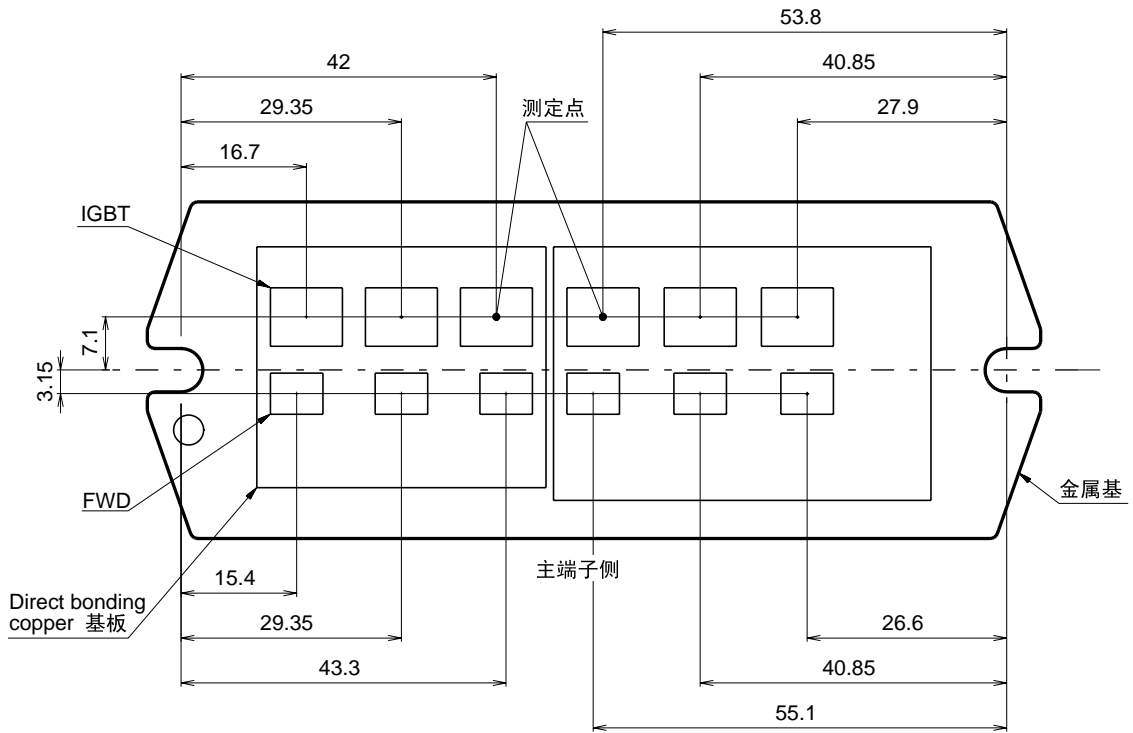


2.2 1200V/50A

7 in one 封装

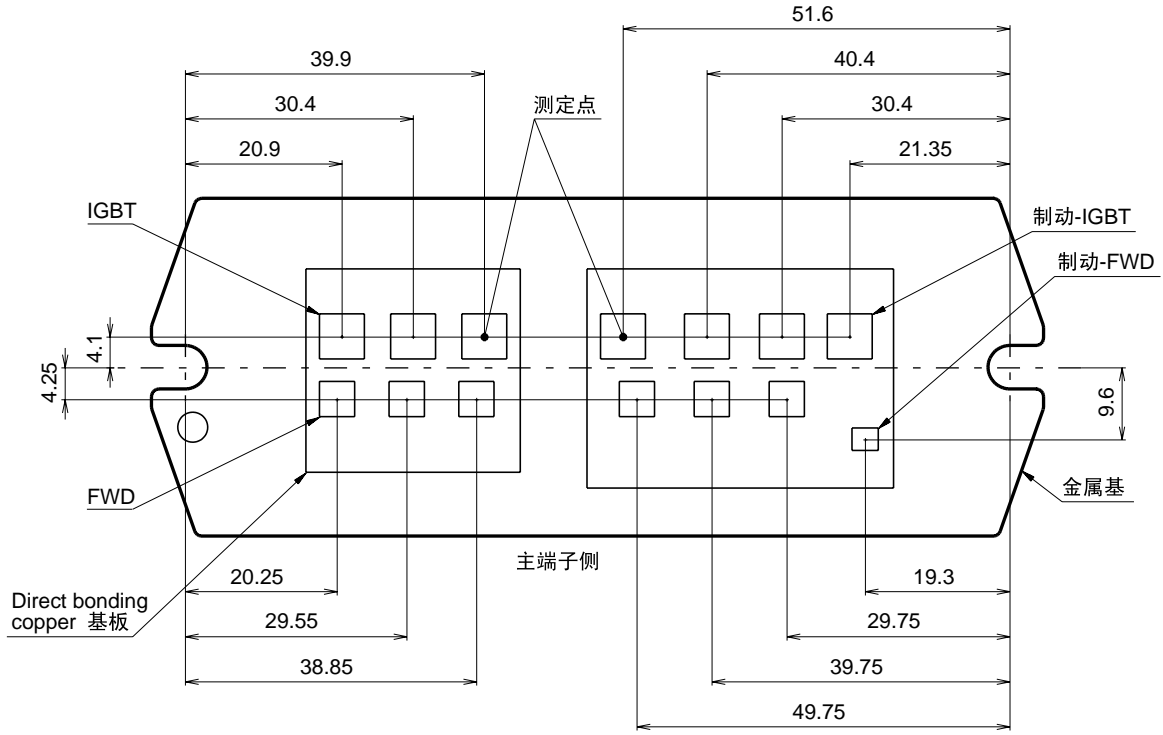


6 in one 封装

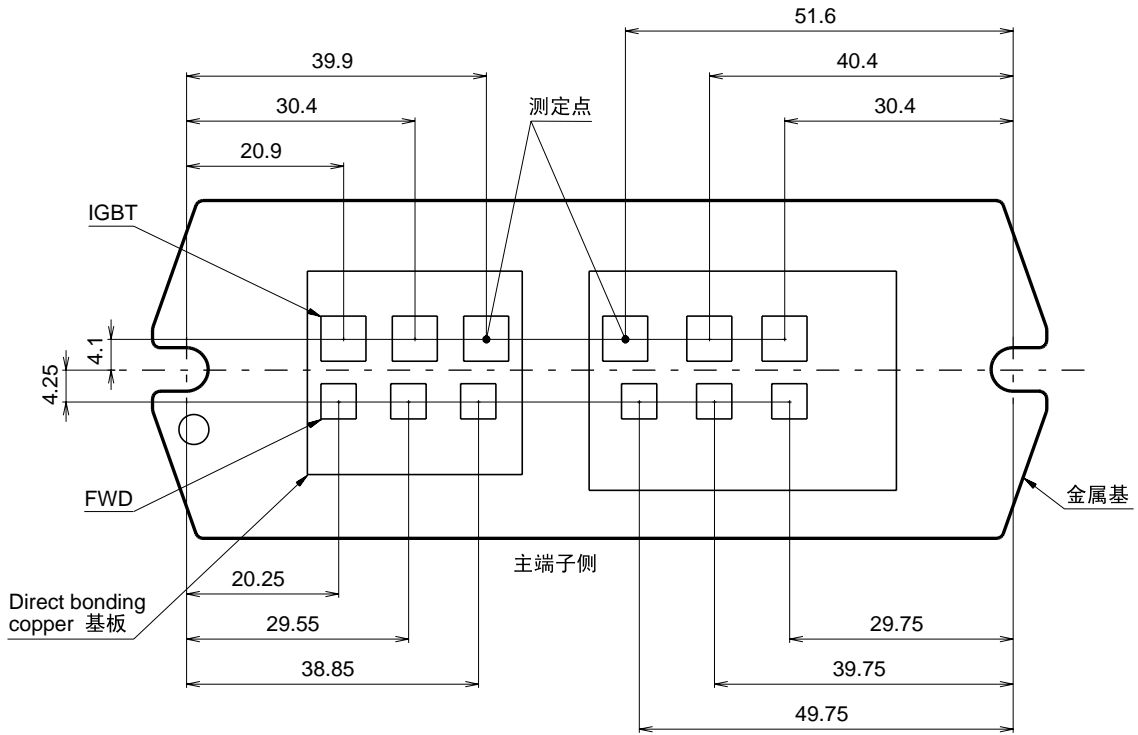


2.3 1200V/25A

7 in one 封装



6 in one 封装

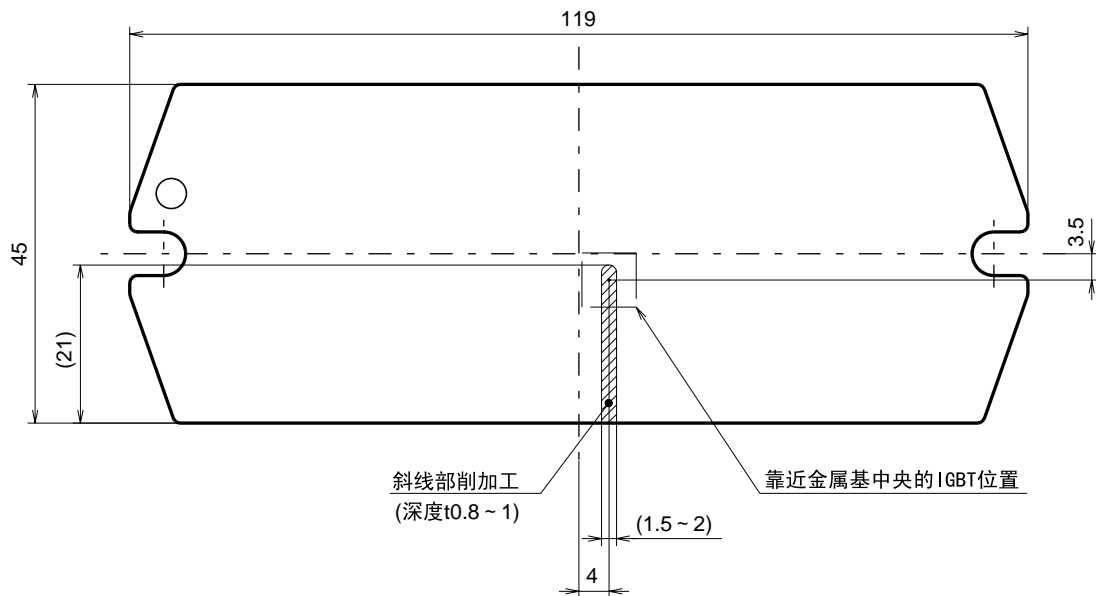


3 外壳温度的测定

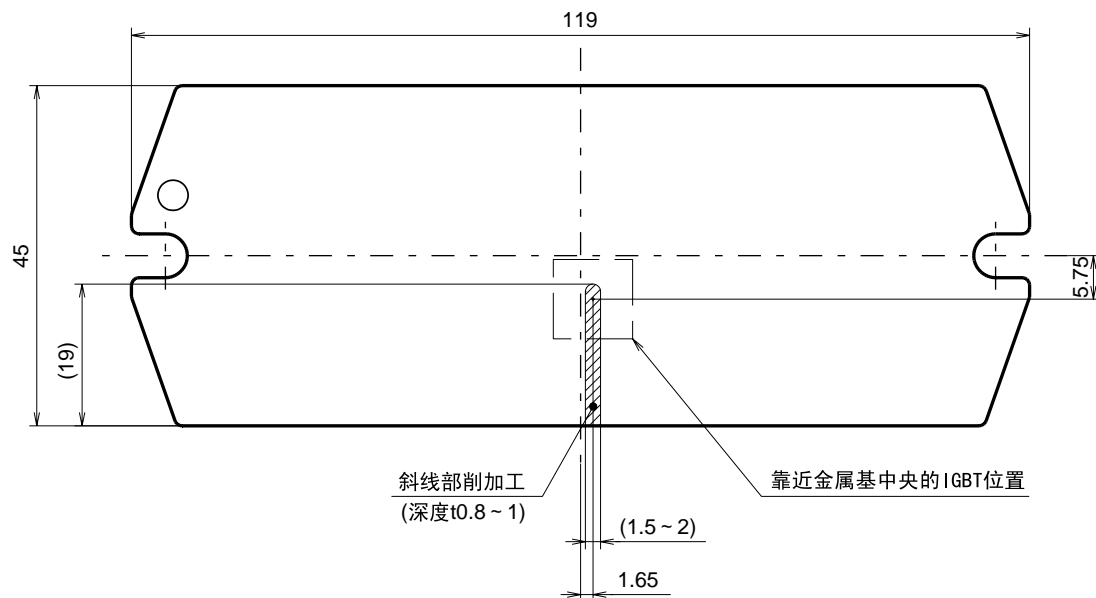
- 请象下图在铜基板后面刻沟。
- 沟的尺寸, 请配合所使用的热电对。
- 请注意如果沟刻得太深, 散热性会变差。
- 请把热电对的异种金属的接合部安装在 IGBT 芯片的直下。
- 用粘着剂把热电对固定, 与沟的间隙用散热绝缘混合剂填埋。

从金属基后面 尺寸是 mm

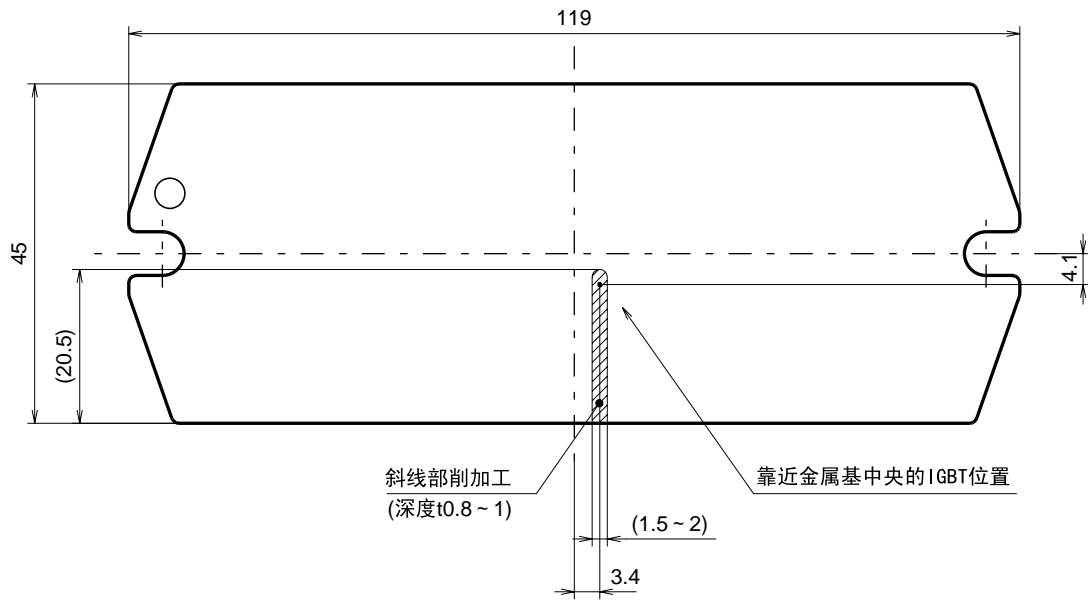
600V/50A、75A: 从金属基后面看时



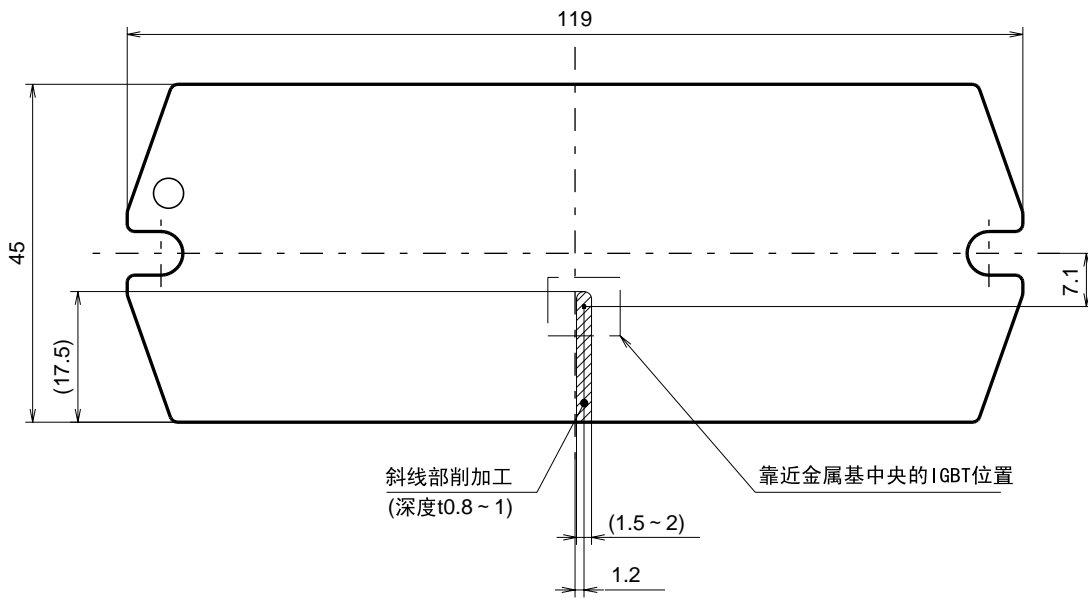
600V/100A、150A、1200V/75A: 从金属基后面看时



1200V/25A: 从金属基后面看时



1200V/50A: 从金属基后面看时



4 R-IPM 系列

芯片配置 尺寸是 mm

4.1 600V/20A (封装: P619)

